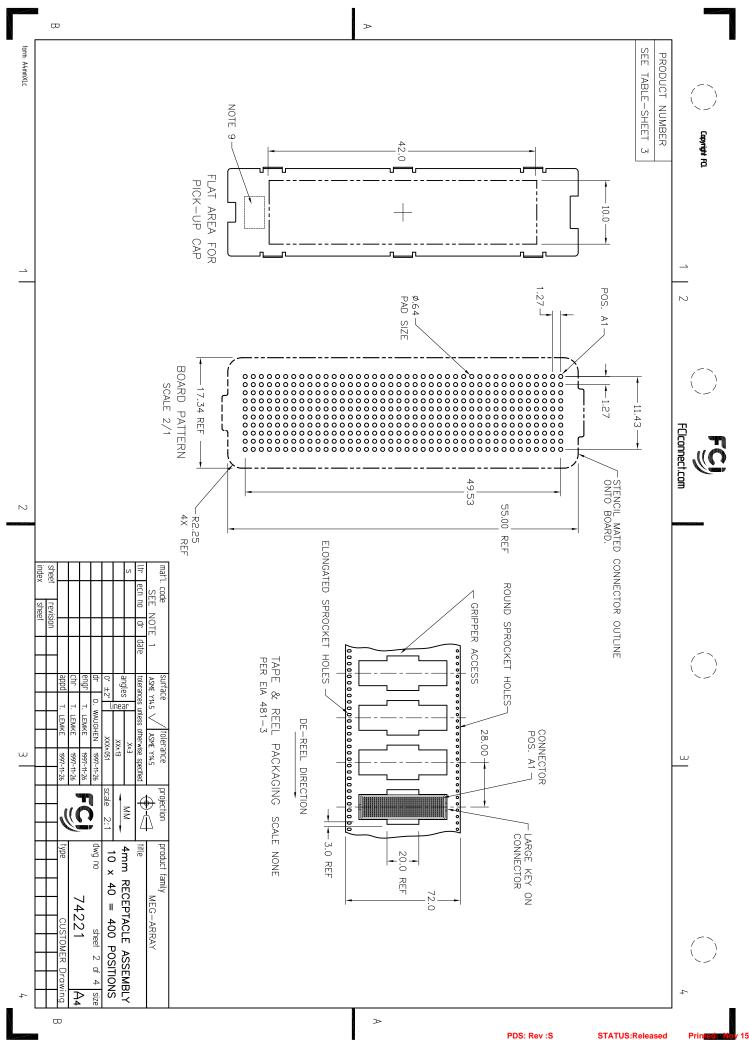
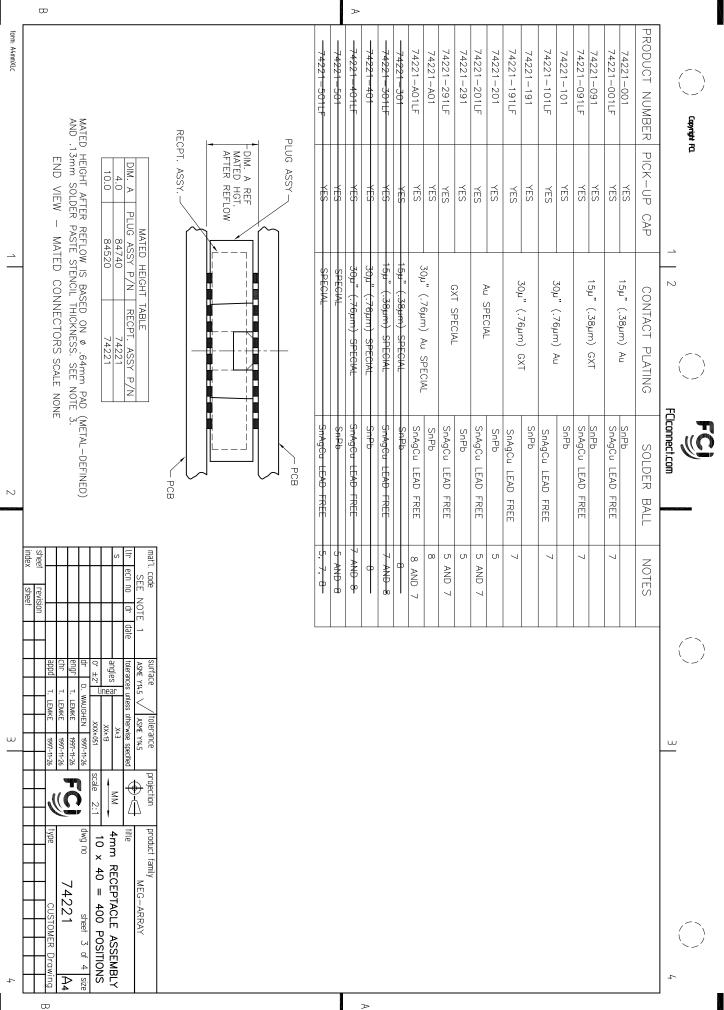


STATUS:Released





PDS: Rev :S

STATUS:Released

May 15, 201

SEE TABLE-SHEET 3

PRODUCT NUMBER

NOTES:

(1.) MATERIAL: HOUSING: LCP

CONTACT: COPPER ALLOY

95.5Sn/4Ag/0.5Cu CONTACT: (SEE TABLE ON SHEET 3)
SOLDER BALL: (SEE TABLE ON SHEET 3)
EUTECTIC SnPb OR LEAD FREE

- 2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- 3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) NO TIN\LEAD OR FLUX ABOVE TERMINAL SHOULDER.
- (5)PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY). THE
- 6. DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL FOR PROPER APPLICATION FOLLOW FCI APPLICATION FCI APPLICATION SPECIFICATION. PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE

- (7.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 IN THE SEVENTH CHARACTER POSITION. CODE NUMBER MARKED ON EACH PART BY HAVING AN "X"
- 74221-A01, -A01LF, HAVE CUSTOMER SPECIAL PLATING

(00)

- (9) CURRENT COMPANY LOGO TO APPROXIMATE AREA SHOWN. BE VISIBLE IN
- <u>1</u>0. HAS BEEN MODIFIED WITH THE CUURRENT DRAWING REVISION. A TRIANGLE SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW, OR NOTE WHICH

11. -301, -301LF, -401, -401LF, -501, -501LF ARE OBOSOLETE

mat'l. code ecn no angles ASME Y14.5 ASME Y14.5 XX±13 2011-06-1 projection **ጥ** ())) ≤ 4mm RECEPTACLE ASSEMBLY ∄e product family ou 6Mp $10 \times 40 = 400$ POSITIONS 74221 MEG-ARRAY

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form: A4mmXLc

2

PDS: Rev :S

STATUS:Released